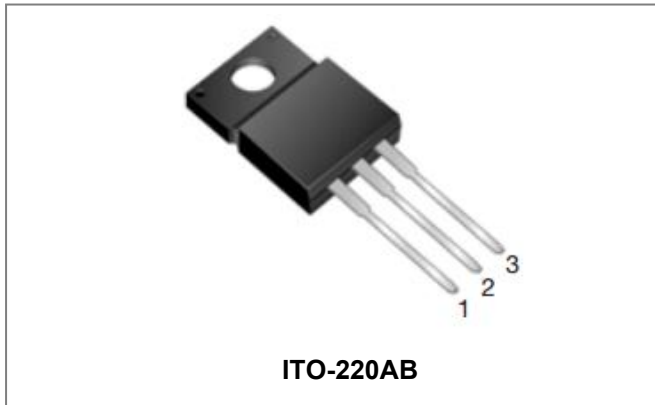


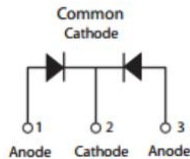
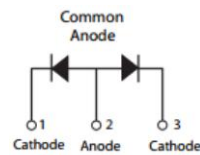
## STF30200C(R) SCHOTTKY RECTIFIER



### Features

- 150 °C T<sub>J</sub> operation
- Ultralow forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Trench MOS Schottky technology
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram


**ST30200C**

**STF30200CR**

### Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

### Maximum Ratings:

Characteristics	Symbol	Condition	Max.	Units
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	-	200	V
Working Peak Reverse Voltage	V <sub>RWM</sub>			
DC Blocking Voltage	V <sub>R</sub>			
Average Rectified Forward Current	I <sub>F(AV)</sub>	50% duty cycle @T <sub>c</sub> =105°C, rectangular wave form	15(Per Leg) 30(Per Device)	A
Peak One Cycle Non-Repetitive Surge Current(Per Leg)	I <sub>FSM</sub>	8.3ms, Half Sine pulse, T <sub>c</sub> =25°C	200	A

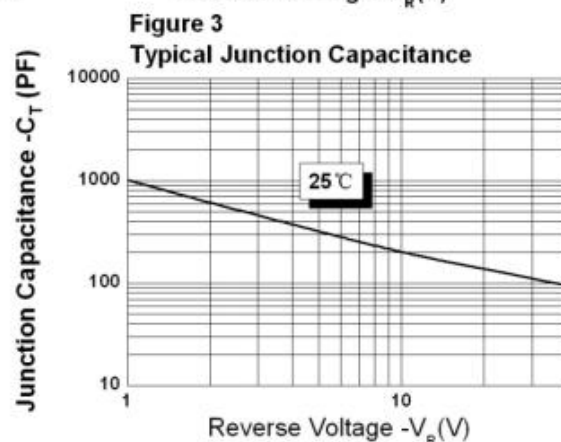
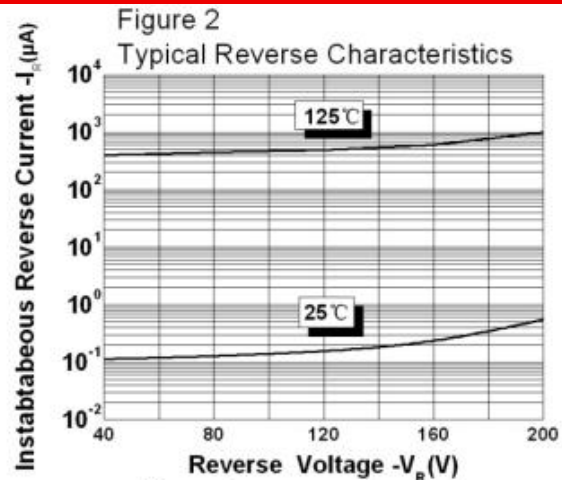
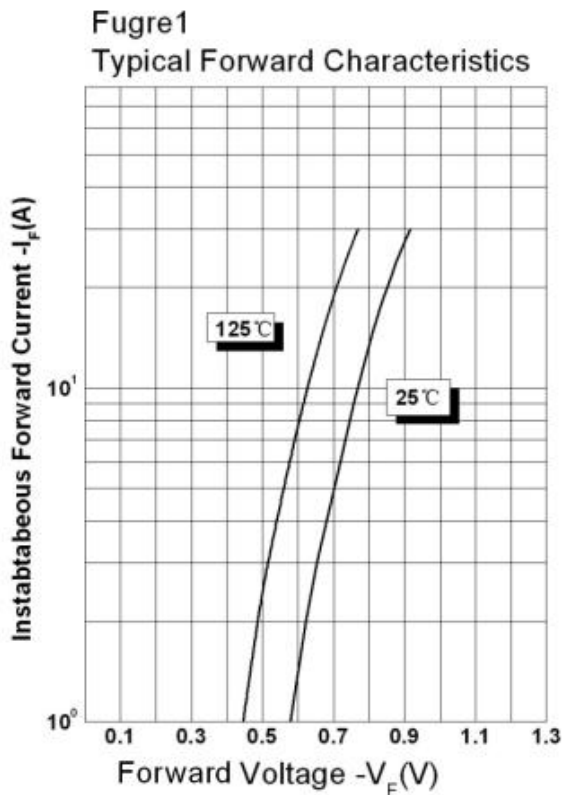
### Thermal-Mechanical Specifications:

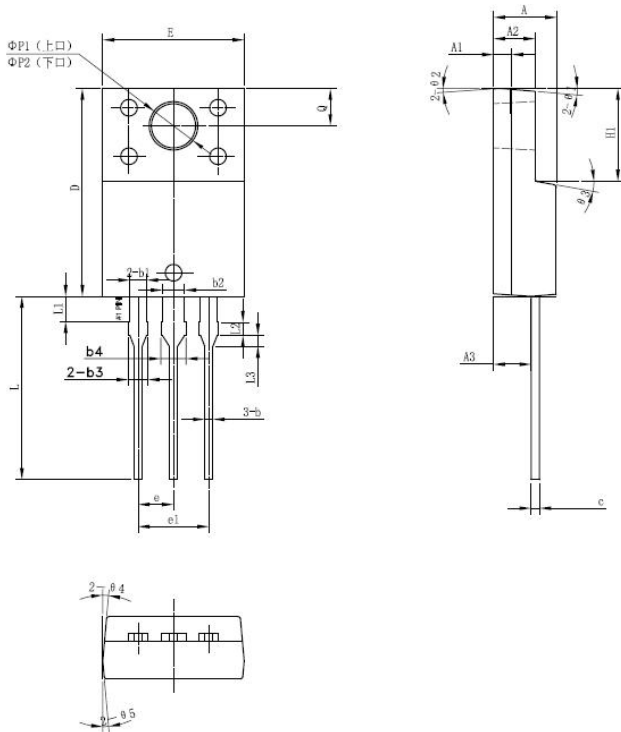
Characteristics	Symbol	Condition	Specification	Units
Junction Temperature	T <sub>J</sub>	-	-55 to +150	°C
Storage Temperature	T <sub>stg</sub>	-	-55 to +150	°C
Typical Thermal Resistance Junction to Case(Per Leg)	R <sub>θJC</sub>	DC operation	5.5	°C/W
Approximate Weight	wt	-	2	g
Case Style	ITO-220AB			

**Electrical Characteristics:**

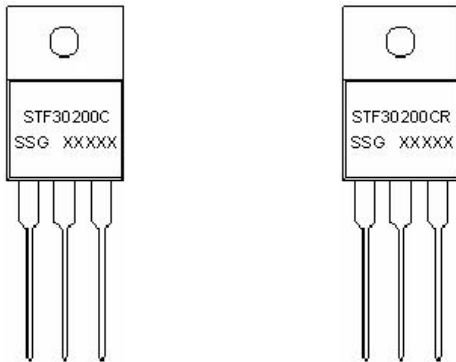
Characteristics	Symbol	Condition	Typ.	Max.	Units
Forward Voltage Drop (Per Leg)*	$V_{F1}$	@ 5A, Pulse, $T_J = 25^\circ\text{C}$	0.70	-	V
		@ 7.5A, Pulse, $T_J = 25^\circ\text{C}$	0.78	-	
@ 15A, Pulse, $T_J = 25^\circ\text{C}$		0.81	1.10		
	$V_{F2}$	@ 5A, Pulse, $T_J = 125^\circ\text{C}$	0.56	-	V
		@ 7.5A, Pulse, $T_J = 125^\circ\text{C}$	0.61	-	
		@ 15A, Pulse, $T_J = 125^\circ\text{C}$	0.68	0.72	
Reverse Current(Per Leg)*	$I_{R1}$	@ $V_R = \text{rated } V_R, T_J = 25^\circ\text{C}$	0.0005	0.16	mA
	$I_{R2}$	@ $V_R = \text{rated } V_R, T_J = 125^\circ\text{C}$	1	12	mA
Junction Capacitance	$C_T$	@ $V_R = 5\text{V}, T_C = 25^\circ\text{C}, f_{\text{SIG}} = 1\text{MHz}$	300	-	pF
RSM Isolation Voltage ( $t = 1.0$ second, R. H. $<= 30\%$ , $T_A = 25^\circ\text{C}$ )	$V_{\text{ISO}}$	Clip mounting, the epoxy body away from the heatsink edge by more than 0.110" along the lead direction.	-	4500	V
		Clip mounting, the epoxy body is inside the heatsink.	-	3500	
		Screw mounting, the epoxy body is inside the heatsink.	-	1500	

\* Pulse width  $< 300 \mu\text{s}$ , duty cycle  $< 2\%$

**Ratings and Characteristics Curves**


**Mechanical Dimensions ITO-220AB**


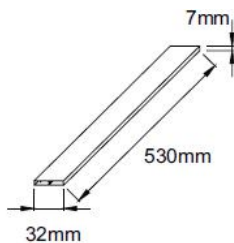
SYMBOL	Millimeters		
	MIN.	TYP.	MAX.
A	4.30	4.50	4.70
A1	1.10	1.30	1.50
A2	2.80	3.00	3.20
A3	2.50	2.70	2.90
b	0.50	0.60	0.75
b1	1.10	1.20	1.35
b2	1.50	1.60	1.75
b3	1.20	1.30	1.45
b4	1.60	1.70	1.85
c	0.50	0.60	0.75
D	14.80	15.00	15.20
E	9.96	10.16	10.36
e		2.55	
e1		5.10	
H1	6.50	6.70	6.90
L	12.70	13.20	13.70
L1	1.60	1.80	2.00
L2	0.80	1.00	1.20
L3	0.60	0.80	1.00
ΦP1(上口)	3.30	3.50	3.70
ΦP2(下口)	2.99	3.19	3.39
Q	2.50	2.70	2.90
Θ1		5°	
Θ2		4°	
Θ3		10°	
Θ4		5°	
Θ5		5°	

**Marking Diagram**


Where XXXXX is YYWWL

- ST = Device Type
- F = Package type
- 30 = Forward Current (30A)
- 200 = Reverse Voltage (200V)
- C(R) = Configuration
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

**Cautions:** Molding resin  
 Epoxy resin UL:94V-0

**Tube Specification**

**Ordering Information**

Device	Package	Shipping
STF30200C(R)	ITO-220AB (Pb-Free)	50 pcs/ tube

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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